



Rev.E Jan.-2021

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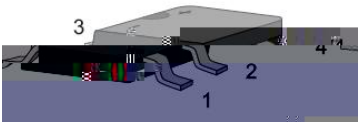
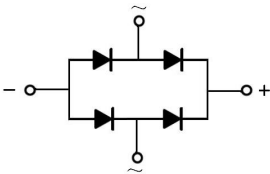


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2.0A MBF
2.0A Surface Mount Schottky Bridge,MBF thin package.

40V~200V 2.0A
High Surge Current Capability,Reverse Voltage:40to200V,Forward Current:2.0A,Designed for Surface Mount Application.Halogen free product.

General purpose.



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



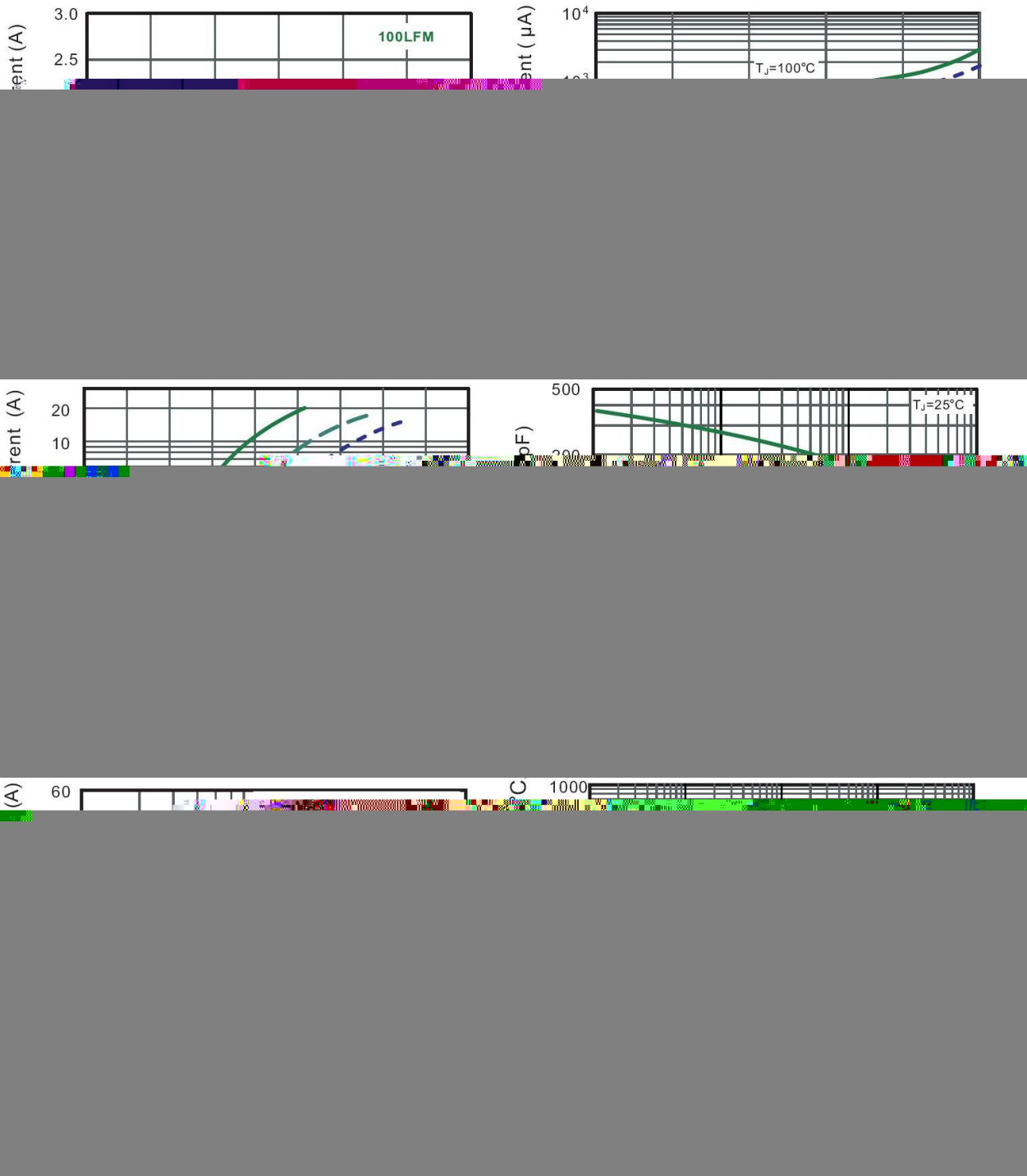
See Marking Instructions.

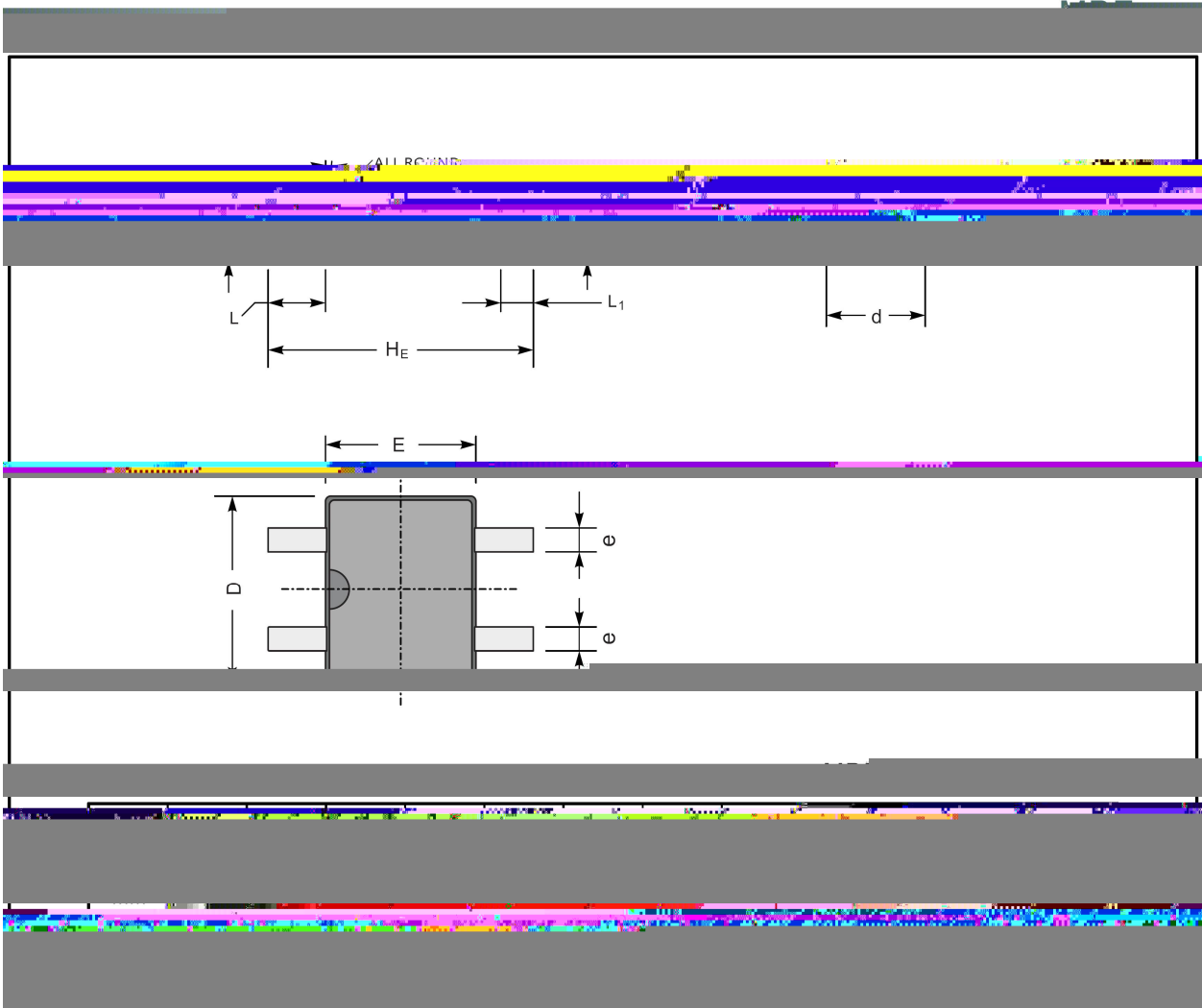


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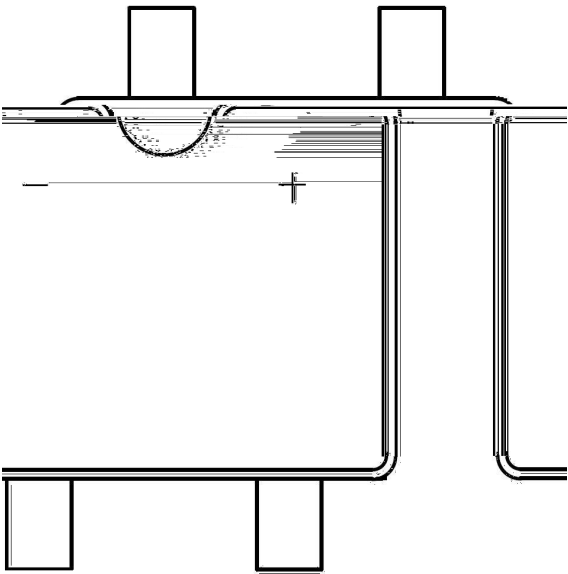
Parameter	Symbol	Rating					Unit
		MB24F	MB26F	MB28F	MB210F	MB220F	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	40	60	80	100	200	V
Maximum RMS Voltage	V _{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V _{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	2.0					A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	50		40			A
Typical Junction Capacitance ¹⁾	C _j	220	80				pF
Typical Thermal Resistance ²⁾	R _{θJA}	75					°C/W

Operating Junction
T





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MB24F

1 *

3 *

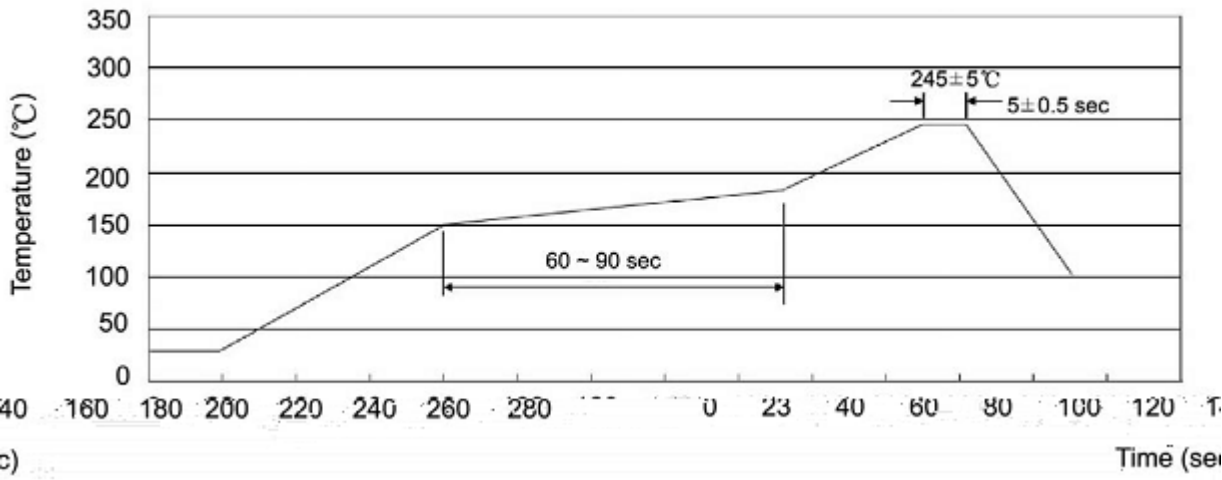
Note:

MB24F Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No Code



Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|-----------|--|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150°C, Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

260±5°C	10±1 sec.	Temp.:260±5°C	Time:10±1 sec
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/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱